John Danison

ECET 32900 - Lab 8

03/28/2025

### Goal:

The goal of this lab was to learn via hands-on methods, how to design a power system for a given embedded system application using Texas Instruments' WEBENCH product.

### **Output:**

WEBENCH report including the schematic, the graphs, the BOM, and other information is attached at the end of this report.

### **Conclusion:**

I learned that designing a custom power system is **significantly** easier to do than I ever knew about. This portion of embedded system hardware design is one that I struggle to get correct on every single personal project that I have ever done. I will absolutely be using this for my own future use in power design. I love the instant ability to have the schematic, BOM, and output graphs all for free.

### **Proof of Signature:**



### References

Texas Instruments. (n.d.). WEBENCH® power designer. Retrieved March 28, 2025, from

https://webench.ti.com/power-designer/

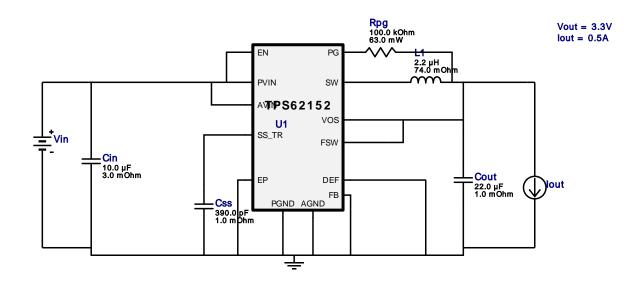
Purdue University. (2025). ECET 32900 Lab 8 instructional documents. Purdue University.



VinMin = 4.0V VinMax = 6.0V Vout = 3.3V Iout = 0.5A Device = TPS62152RGTR Topology = Buck Created = 2025-03-14 14:51:27.361 BOM Cost = \$0.73 BOM Count = 6 Total Pd = 0.1W

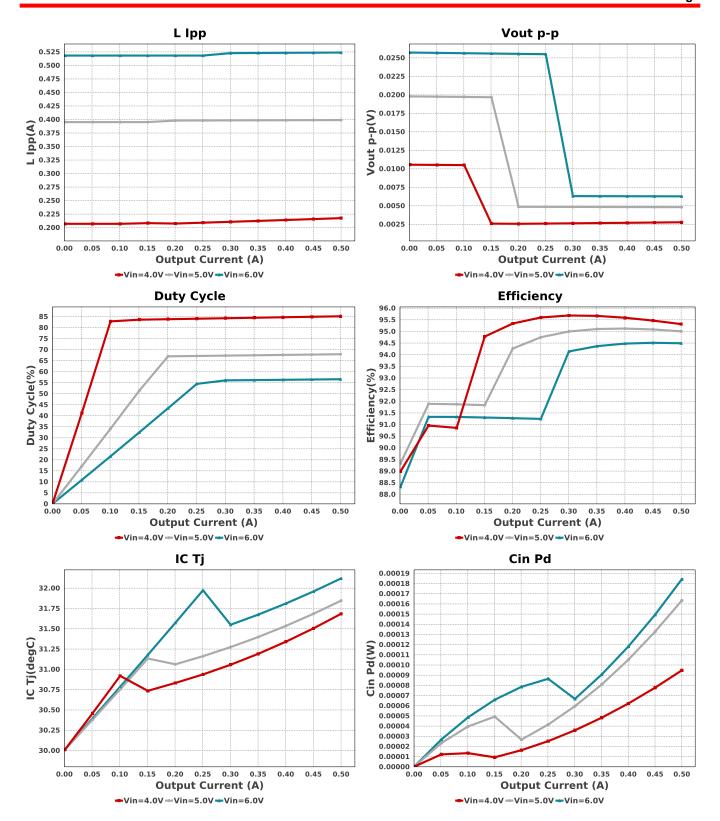
# WEBENCH® Design Report

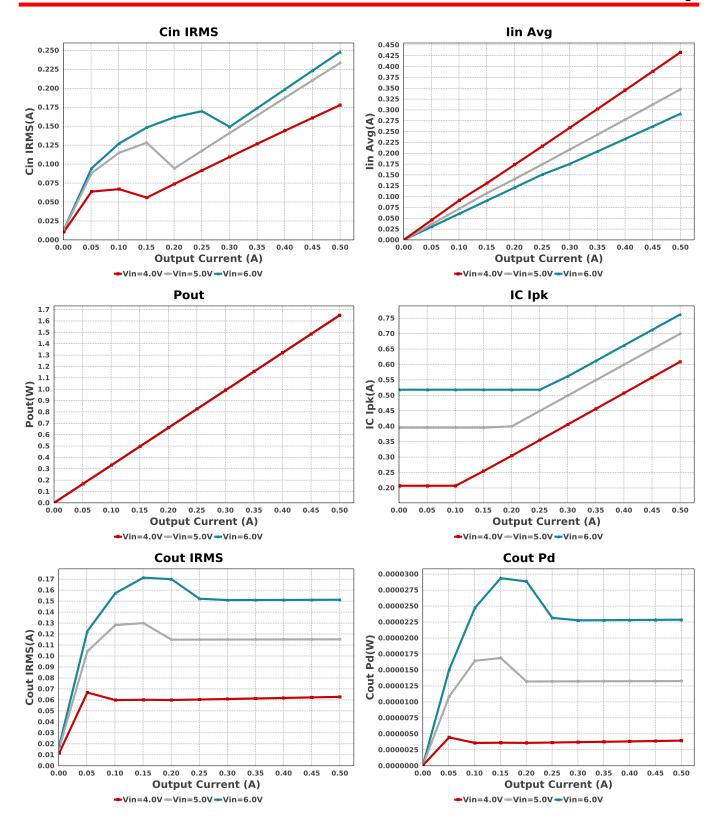
Design: 1 TPS62152RGTR TPS62152RGTR 4V-6V to 3.30V @ 0.5A

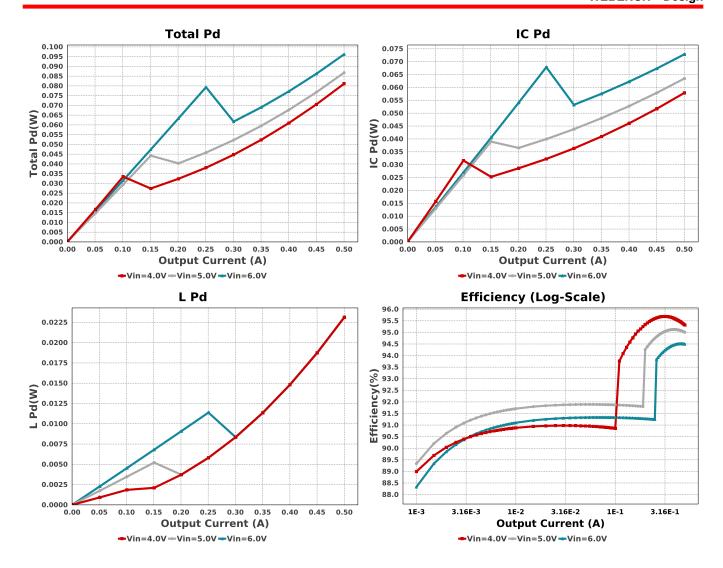


### **Electrical BOM**

| Name | Manufacturer      | Part Number                        | Properties  | Qty | Price  | Footprint                   |
|------|-------------------|------------------------------------|---|-----|--------|-----------------------------|
| Cin  | Kemet             | C0805C106K8PACTU<br>Series= X5R    | Cap= 10.0 uF<br>ESR= 3.0 mOhm<br>VDC= 10.0 V<br>IRMS= 11.43 A | 1   | \$0.03 | 0805 7 mm <sup>2</sup>      |
| Cout | MuRata            | GRM188R60J226MEA0D<br>Series= X5R  | Cap= 22.0 uF<br>ESR= 1.0 mOhm<br>VDC= 6.3 V<br>IRMS= 6.0 A    | 1   | \$0.04 | 0603 5 mm <sup>2</sup>      |
| Css  | MuRata            | GRM033R71C391KA01D<br>Series= X7R  | Cap= 390.0 pF<br>ESR= 1.0 mOhm<br>VDC= 16.0 V<br>IRMS= 0.0 A  | 1   | \$0.01 | 0201 2 mm <sup>2</sup>      |
| L1   | TDK               | VLS3012CX-2R2M-1                   | L= 2.2 μH<br>74.0 mOhm  | 1   | \$0.14 | VLS3012 16 mm <sup>2</sup>  |
| Rpg  | Vishay-Dale       | CRCW0402100KFKED<br>Series= CRCWe3 | Res= 100.0 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0%          | 1   | \$0.01 | 0402 3 mm <sup>2</sup>      |
| U1   | Texas Instruments | TPS62152RGTR                       | Switcher  | 1   | \$0.50 | •                           |
|      |                   |                                    |   |     |        | RGT0016C 16 mm <sup>2</sup> |







#### Operating Values

| -   : | ialing values |                      |             |   |
|-------|---------------|----------------------|-------------|---|
| #     | Name          | Value                | Category    | Description                               |
| 1.    | Cin IRMS      | 247.82 mA            | Capacitor   | Input capacitor RMS ripple current        |
| 2.    | Cin Pd        | 184.24 μW            | Capacitor   | Input capacitor power dissipation         |
| 3.    | Cout IRMS     | 151.209 mA           | Capacitor   | Output capacitor RMS ripple current       |
| 4.    | Cout Pd       | 22.864 μW            | Capacitor   | Output capacitor power dissipation        |
| 5.    | IC lpk        | 761.902 mA           | IC          | Peak switch current in IC                 |
| 6.    | IC Pd         | 72.855 mW            | IC          | IC power dissipation                      |
| 7.    | IC Tj         | 32.12 degC           | IC          | IC junction temperature                   |
| 8.    | ICThetaJA     | 29.1 degC/W          | IC          | IC junction-to-ambient thermal resistance |
| 9.    | lin Avg       | 291.03 mA            | IC          | Average input current                     |
| 10.   | L lpp         | 523.8 mA             | Inductor    | Peak-to-peak inductor ripple current      |
| 11.   | L Pd          | 23.125 mW            | Inductor    | Inductor power dissipation                |
| 12.   | Cin Pd        | 184.24 μW            | Power       | Input capacitor power dissipation         |
| 13.   | Cout Pd       | 22.864 µW            | Power       | Output capacitor power dissipation        |
| 14.   | IC Pd         | 72.855 mW            | Power       | IC power dissipation                      |
| 15.   | L Pd          | 23.125 mW            | Power       | Inductor power dissipation                |
| 16.   | Total Pd      | 96.18 mW             | Power       | Total Power Dissipation                   |
| 17.   | BOM Count     | 6                    | System      | Total Design BOM count                    |
|       |               |                      | Information |   |
| 18.   | Duty Cycle    | 56.589 %             | System      | Duty cycle                                |
|       |               |                      | Information | • •                                       |
| 19.   | Efficiency    | 94.492 %             | System      | Steady state efficiency                   |
|       | ·             |                      | Information | ·   |
| 20.   | FootPrint     | 49.0 mm <sup>2</sup> | System      | Total Foot Print Area of BOM components   |
|       |               |                      | Information | ·   |
| 21.   | Frequency     | 1.326 MHz            | System      | Switching frequency                       |
|       |               |                      | Information |   |
| 22.   | lout          | 500.0 mA             | System      | lout operating point                      |
|       |               |                      | Information |   |
| 23.   | Mode          | CCM                  | System      | Conduction Mode                           |
|       |               |                      | Information |   |
| 24.   | Pout          | 1.65 W               | System      | Total output power                        |
|       |               |                      | Information |   |

| #   | Name           | Value    | Category              | Description  |
|-----|----------------|----------|-----------------------|--|
| 25. | Total BOM      | \$0.73   | System<br>Information | Total BOM Cost   |
| 26. | Vin            | 6.0 V    | System<br>Information | Vin operating point  |
| 27. | Vout           | 3.3 V    | System<br>Information | Operational Output Voltage   |
| 28. | Vout Tolerance | 1.8 %    | System<br>Information | Vout Tolerance based on IC Tolerance (full load) and voltage divider resistors if applicable |
| 29. | Vout p-p       | 6.278 mV | System<br>Information | Peak-to-peak output ripple voltage   |

# **Design Inputs**

| Name    | Value    | Description            |  |
|---------|----------|------------------------|--|
| lout    | 500.0 m  | Maximum Output Current |  |
| VinMax  | 6.0      | Maximum input voltage  |  |
| VinMin  | 4.0      | Minimum input voltage  |  |
| Vout    | 3.3      | Output Voltage         |  |
| base_pn | TPS62152 | Base Product Number    |  |
| source  | DC       | Input Source Type      |  |
| Та      | 30.0     | Ambient temperature    |  |

### WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 4.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

#### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

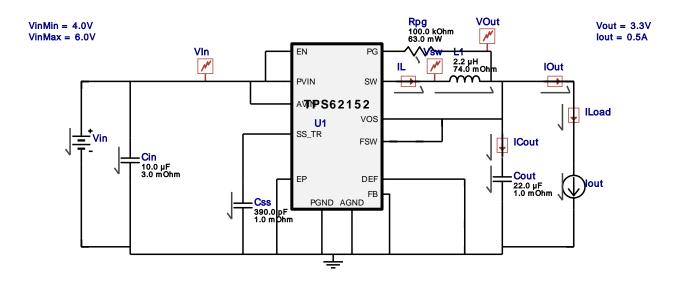


# **WEBENCH®** Electrical Simulation Report

Design Id = 1

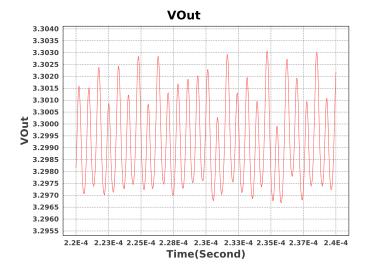
sim\_id = 1

Simulation Type = Steady State



### Simulation Parameters

| # Name      | Parameter Name | Description  | Values |
|-------------|----------------|--------------|--------|
| <br>1. lout | ·              | Load Current | 0.5 A  |



### Design Assistance

- 1. Feature Highlights: DCS-Control(TM) Architecture with upto 1A output current, 3V to 17V Input Voltage Range, 3.3V Fixed Output voltageSelectable operating frequency, Optional Softstart Capacitor for slow startup, Tracking,Pin selectable output voltage (nominal, +5%) Seamless Power Save Mode for Light Load Efficiency, Power Good Output, 100% Duty Cycle mode, Short Circuit Protection, Thermal Shutdown
- 2. Master key: 3B1EC955F3A3AF9BB76B7EF2215CD094[v1]
- 3. **TPS62152** Product Folder: http://www.ti.com/product/TPS62152: contains the data sheet and other resources.

#### Important Notice and Disclaimer

TI provides technical and reliability data (including datasheets), design resources (including reference designs), application or other design advice, web tools, safety information, and other resources AS IS and with all faults, and disclaims all warranties. These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Providing these resources does not expand or otherwise alter TI's applicable Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with TI products.